



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



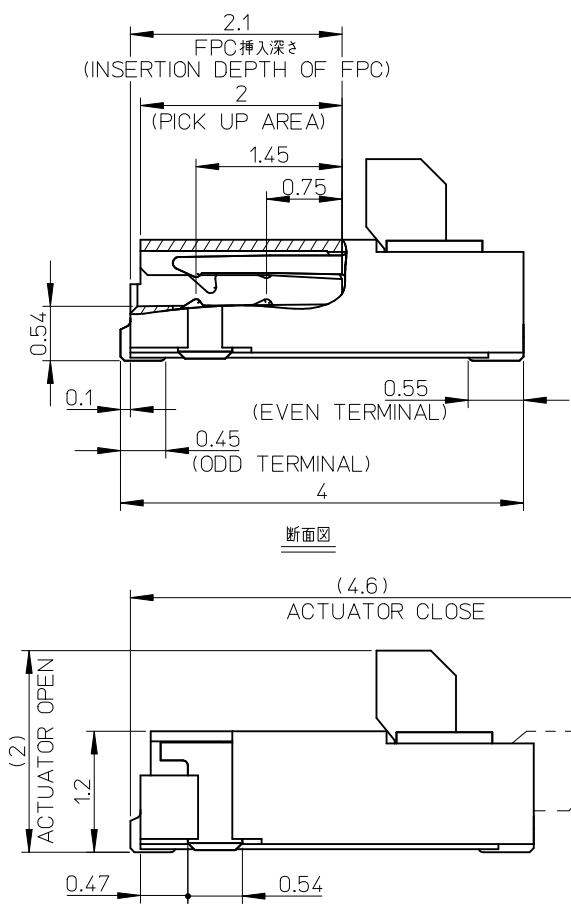
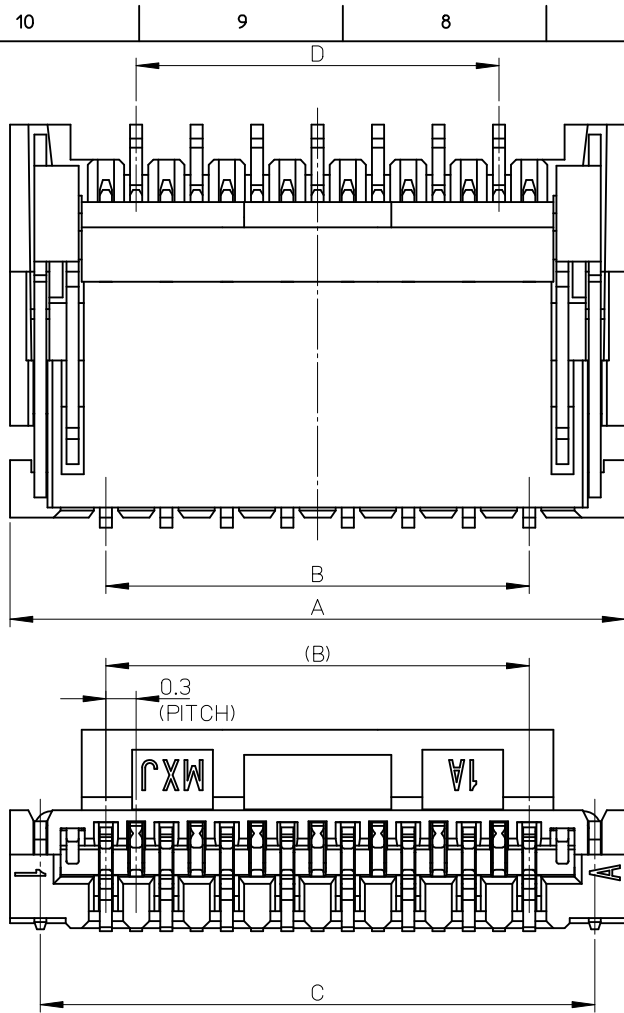
## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





注記  
NOTES:

1.材質  
MATERIAL  
ハウジング:液晶ポリマー(LCP)、ナチュラル(白)、ガラス充填、UL94V-0  
HOUSING: LIQUID CRYSTAL POLYMER(LCP), NATURAL (WHITE)  
GLASS FILLED, UL94V-0  
アクチュエータ:ポリフェニレンサルファイド(PPS)、黒色、ガラス充填、UL94V-0  
ACTUATOR: POLYPHENYLENE SULFIDE(PPS), BLACK  
GLASS FILLED, UL94V-0  
ターミナル:銅合金(t=0.12)  
TERMINAL: COPPER ALLOY(t=0.12)  
金具:リン青銅(t=0.12)  
NAIL: PHOS-BRO(t=0.12)

2.めっき仕様  
PLATING  
ターミナル  
TERMINAL  
接点部:金めっき 0.1μm以上  
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM.  
半田付け部:金めっき  
SOLDER TAIL AREA: GOLD  
下地めっき:ニッケル 1.0μm以上  
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM.  
金具  
NAIL  
錫めっき 1.0μm以上  
TIN PLATING 1.0 MICROMETER MINIMUM.  
下地めっき:ニッケル 1.0μm以上  
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM.

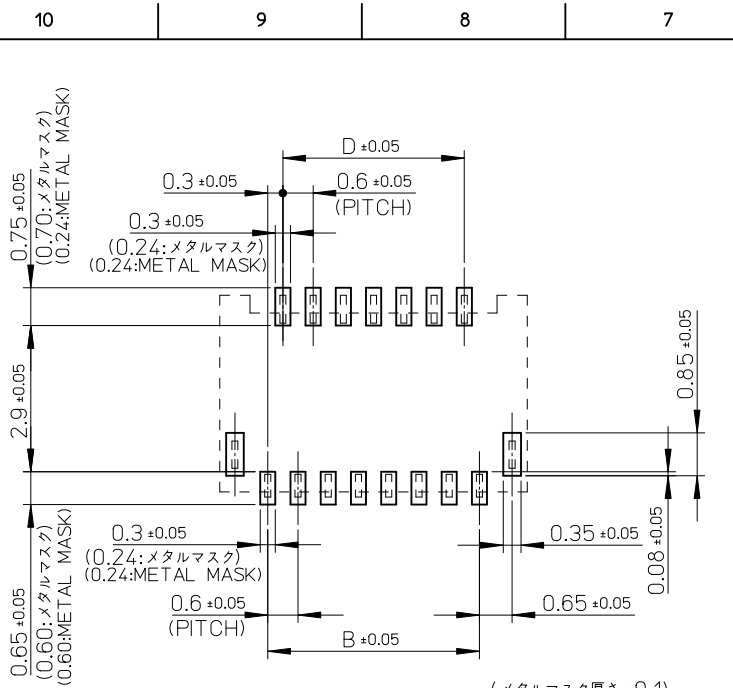
3.平坦度は、0.1ミリ以下とする。  
TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

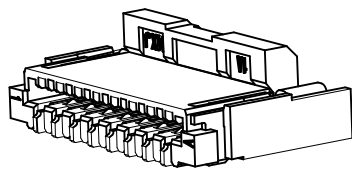
0.208	21.6	23.5	22.2	24.1	503425-7591	75
0.171	17.4	19.3	18.0	19.9	503425-6191	61
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 503425-xx11

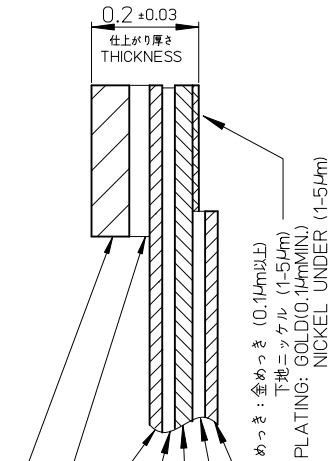
RELEASED EC NO.: J2010-2422 DRW: KUSATO 2009/04/28 CHK: HSHIMOYAMA 2010/05/28 APPR: KMORIKAWA 2010/05/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY KUSATO	DATE 2008/11/14	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY	
	10 OVER 30 UNDER	±0.25	CHECKED BY HSHIMOYAMA	DATE 2008/11/14	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY HHRATA	DATE 2008/11/14	DOCUMENT NO. SD-503425-001	SHEET NO. 1 OF 2
	ANGULAR ±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



推奨基板寸法  
RECOMMENDED P.W.B. PATTERN LAYOUT  
(メタルマスク厚さ: 0.1)  
(METAL MASK THICKNESS: 0.1)

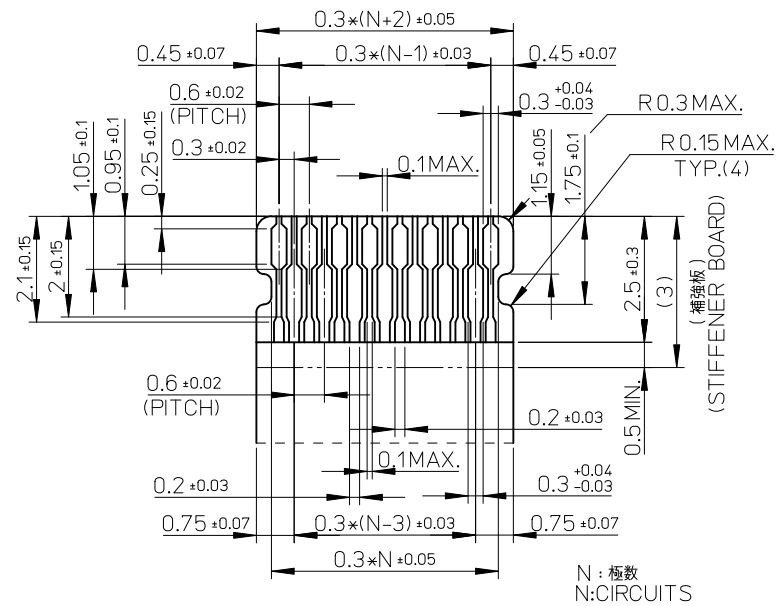


ISO VIEW (参考)



- 補強板: ポリイミド REINFORCE BOARD: POLYIMIDE
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- ベースフィルム: ポリイミド (25µm) BASE FILM: POLYIMIDE (25µm)
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- 導体部: 銅箔 (35µm) CONDUCTOR: COPPER FOIL (35µm)
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- カバーレイ: ポリイミド (25µm) COVER FILM: POLYIMIDE (25µm)

FPC構成推奨仕様  
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法  
APPLICABLE FPC OF GOLD PATING  
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2 ± 0.03)  
(THICKNESS: 0.2 ± 0.03)

FPCについて:

- 抜き方向は、導体側から補強板側を推奨致します。
- 補強フィルム材質は、ポリイミドを推奨致します。
- 接着剤は熱硬化接着剤を推奨致します。
- 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC:

- RECOMMENDED PUNCHER DIRECTION:  
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
- RECOMMENDED MATERIAL:  
STIFFENER FILM: POLYIMIDE  
BONDING AGENT: THERMOSETTING AGENT
- PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND  
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE  
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

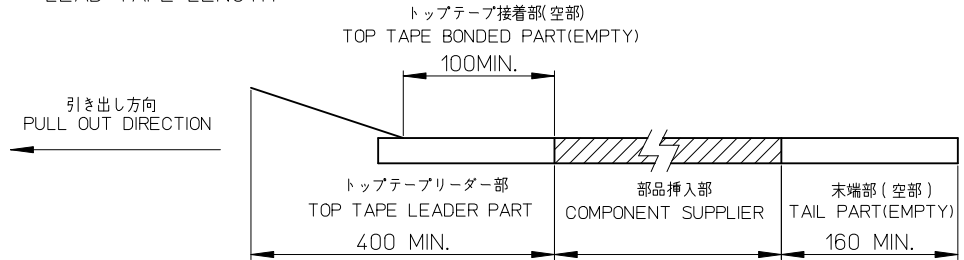
SEE SHEET 1 EC NO: J2010-2422 DRWN: KUSATO 2009/04/28 CHKD: HSHIMOYAMA 2010/05/28 APPR: KMORIKAWA 2010/05/31	DESCRIPTION REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION			
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE	MOLEX INCORPORATED SD-503425-001 2 OF 2				
		10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE	0.3 FPC CONN. BACK FLIP HOUSING ASSY					
		30 OVER	± 0.3	APPROVED BY	DATE						
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		DOCUMENT NO.		SHEET NO.			
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

注記)  
NOTES

1. 製品番号503425-\*\*11の詳細寸法は、製品単体図面を参照下さい。  
IN THE PACKAGE PART NUMBER 503425-\*\*11 DETAIL DIMENSIONS,  
SEE SALES DRAWING FOR CONNECTOR.

2. 梱包数量: 3000個/リール  
NUMBER OF CONNECTORS: 3000 PCS/REEL

3. リードテープ長さ  
LEAD TAPE LENGTH



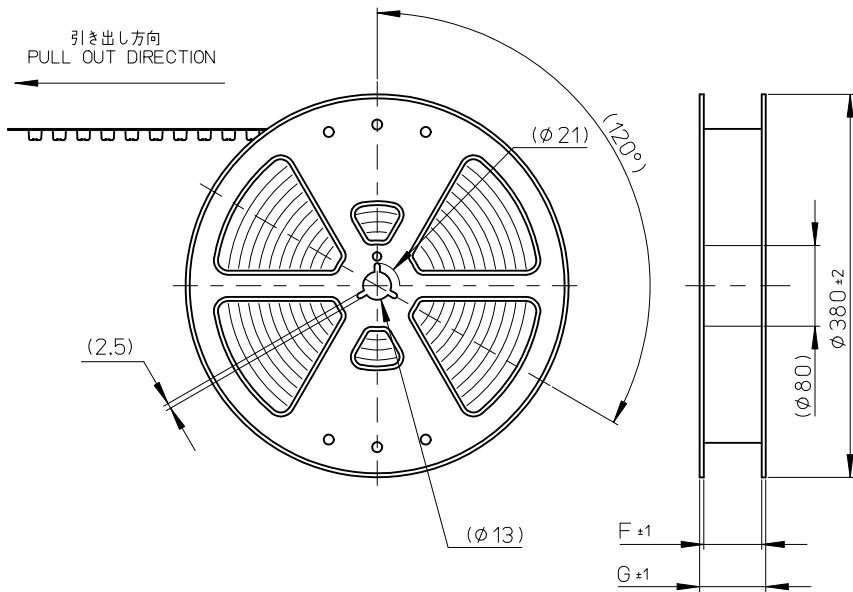
4. カバーテープの剥離強度については、IEC60286-3に準拠  
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

5. 材料

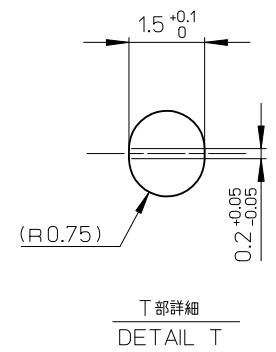
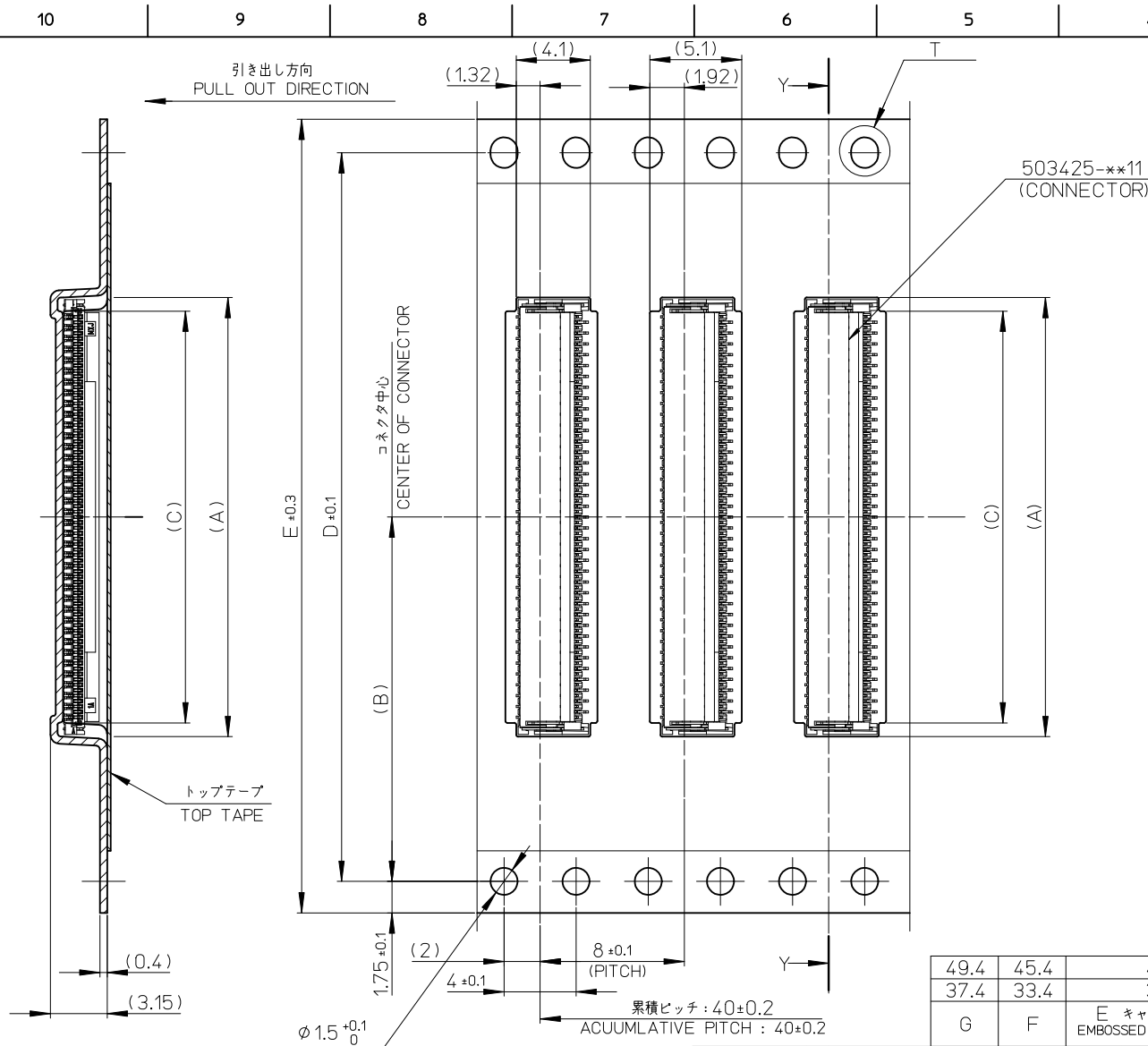
MATERIAL

キャリアテープ: ポリスチレン (PS)  
CARRIER TAPE: POLYSTYRENE (PS)  
トッテープ: PET, PE, PEF  
TOP TAPE: PET, PE, PEF  
リール: ポリスチレン  
REEL: POLYSTYLENE

6. ELV及びRoHS適合品  
ELV AND LoHS COMPLIANT



RELEASED EC NO: J2010-2422 DRW: KUSATO 2008/11/19 CH'D: HSHIMOYAMA 2010/05/28 APPR: KMORIKAWA 2010/05/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	$\pm$ ---	DRAWN BY KUSATO	DATE 2008/11/19	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (503425-**11 SERIES)			
	10 OVER 30 UNDER	$\pm$ ---	CHECKED BY HSHIMOYAMA	DATE 2008/11/19				
	30 OVER	$\pm$ ---	APPROVED BY HHRATA	DATE 2008/11/19	MOLEX INCORPORATED			
	ANGULAR $\pm 1^\circ$		MATERIAL NO. SEE SHEET 1 OF 2					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



49.4	45.4	44	40.4	22.82	20.2	24.35	503425-7591	75	
37.4	33.4	32	28.4	18.62	14.2	20.15	503425-6191	61	
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH		D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

SEE SHEET 1 OF 2 EC NO: J2010-2422 DRWN: KUSATO 2008/11/27 CH'KD: HSHIMUYAMA 2010/05/28 APPR: KMORI/KAWA 2010/05/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY KUSATO	DATE 2008/11/19	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (503425-**11 SERIES)			
	10 OVER 30 UNDER	± ---	CHECKED BY HSHIMUYAMA	DATE 2008/11/19				
	30 OVER	± ---	APPROVED BY HHIRATA	DATE 2008/11/19				
	ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		MOLEX INCORPORATED		SD-503425-002		
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						